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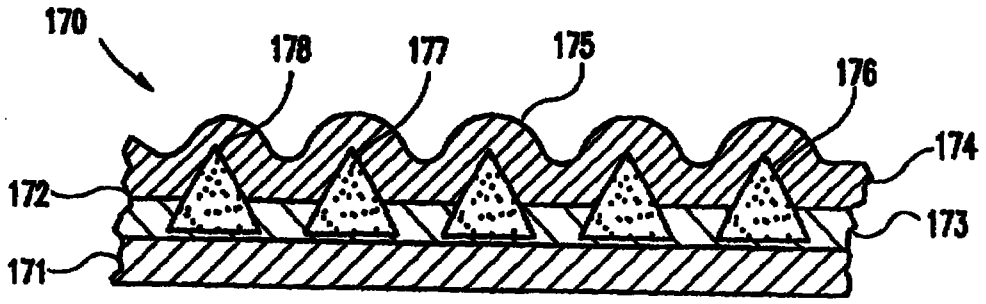
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(54) Title: METHOD OF MODIFYING AN EXPOSED SURFACE OF A SEMICONDUCTOR WAFER



(57) Abstract

A method of modifying an exposed surface of a semiconductor wafer that includes the steps of: (a) contacting the surface with a fixed abrasive article having a three-dimensional textured abrasive surface that includes a plurality of abrasive particles and a binder in the form of a pre-determined pattern; and (b) relatively moving the wafer and the fixed abrasive article to modify said surface of the wafer.